



Meta MTIA 300

MTIA

2026

OVERVIEW

— FP32 TFLOPS	216 GB VRAM HBM	6.1 TB/s Memory Bandwidth	800 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
FP8	1200.0	8	Standard
BF16	600.0	16	Standard

MEMORY SPECIFICATIONS

Capacity	216 GB
Type	HBM
Bandwidth	6.1 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	800 W
Est. Max Power	920 W
FP32 Efficiency	—
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Meta	Architecture: MTIA	Process Node: —
Form Factor: —	Launch Year: 2026	

CHIP DESIGN

Chiplets: 3 (1 compute chiplet, 2 network chiplets, several HBM stacks)